SN54121, SN74121 MONOSTABLE MULTIVIBRATORS WITH SCHMITT-TRIGGER INPUTS

MAY 1983 - REVISED MARCH 1988

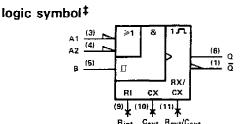
- Programmable Output Pulse Width
 With R_{int}...35 ns Typ
 With R_{ext}/C_{ext}...40 ns to 28 Seconds
- Internal Compensation for Virtual Temperature Independence
- Jitter-Free Operation up to 90% Duty Cycle
- Inhibit Capability

SN74121	J OR W PACKAGE N PACKAGE OP VIEWI
Q 1 NC 2 A1 3 A2 4 B 5 Q 6 GND 7	14 VCC 13 NC 12 NC 11 Rext/Cext 10 Cext 9 Rint 8 NC

NC - No internal connection.

FUNCTION TABLE

IP	NPU TS	OUTPUTS	
A1	A2	В	0 0
L	Х	H	L H
X	L	H	Lt Ht
x	х	L	Lt Ht
Н	Н	X	Lt Ht
Н	1	Н	
1	H	н	
l l	i	Н	
Ļ	х	t	▎▗╌╶┰╴
L.x	L	1	



[‡]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

For explanation of function table symbols, see page

† These lines of the function table assume that the indicated steady-state conditions at the A and B inputs have been setup long enough to complete any pulse started before the setup.

description

These multivibrators feature dual negative-transition-triggered inputs and a single positive-transition-triggered input which can be used as an inhibit input. Complementary output pulses are provided.

Pulse triggering occurs at a particular voltage level and is not directly related to the transition time of the input pulse. Schmitt-trigger input circuitry (TTL hysteresis) for the B input allows jitter-free triggering from inputs with transition rates as slow as 1 volt/second, providing the circuit with an excellent noise immunity of typically 1.2 volts. A high immunity to VCC noise of typically 1.5 volts is also provided by internal latching circuitry.

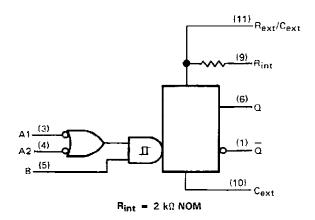
Once fired, the outputs are independent of further transitions of the inputs and are a function only of the timing components. Input pulses may be of any duration relative to the output pulse. Output pulse length may be varied from 40 nanoseconds to 28 seconds by choosing appropriate timing components. With no external timing components (i.e., R_{int} connected to V_{CC}, C_{ext} and R_{ext}/C_{ext} open), an output pulse of typically 30 or 35 nanoseconds is achieved which may be used as a d-c triggered reset signal. Output rise and fall times are TTL compatible and independent of pulse length.

Pulse width stability is achieved through internal compensation and is virtually independent of V_{CC} and temperature. In most applications, pulse stability will only be limited by the accuracy of external timing components.

Jitter-free operation is maintained over the full temperature and VCC ranges for more than six decades of timing capacitance (10 pF to 10 μ F) and more than one decade of timing resistance (2 k Ω to 30 k Ω for the SN54121 and 2 k Ω to 40 k Ω for the SN74121). Throughout these ranges, pulse width is defined by the relationship $t_{W(out)} = C_{ext}R_{T}\ln 2 \approx 0.7~C_{ext}R_{T}$. In circuits where pulse cutoff is not critical, timing capacitance up to 1000 μ F and timing resistance as low as 1.4 k Ω may be used. Also, the range of jitter-free output pulse widths is extended if V_{CC} is held to 5 volts and free-air temperature is 25 °C. Duty cycles as high as 90% are achieved when using maximum recommended R_T'. Higher duty cycles are available if a certain amount of pulse-width jitter is allowed.



logic diagram (positive logic)

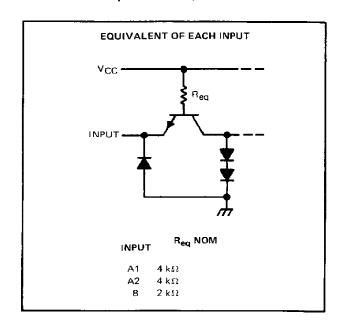


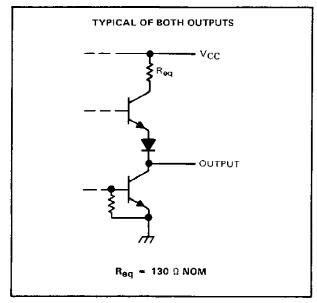
Pin numbers shown on logic notation are for J or N packages.

NOTES: 1. An external capacitor may be connected between C_{ext} (positive) and R_{ext}/C_{ext} .

2. To use the internal timing resistor, connect R_{int} to V_{CC} . For improved pulse width accuracy and repeatability, connect an external resistor between R_{ext}/C_{ext} and V_{CC} with Rint open-circuited.

schematics of inputs and outputs





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 3)	٧
Input voltage	٧
Operating free-air temperature range: SN5412155°C to 125°C	С
SN74121 0°C to 70°C	С
Storage temperature range65°C to 150°C	С

NOTE 3: Voltage values are with respect to network ground terminal.

recommended operating conditions

				MIN	NOM	MAX	UNIT
Vcc	Supply voltage	•	54 Family	4.5	5	5.5	v
•	Supply voltage		74 Family	4.75	5	5.25	\ \ \
Іон	High-level output current					-0.4	mA
JOL	Low-level output current					16	mA
dv/dt	Rate of rise or fall of input pulse	Schmitt input, B		1			V/s
GV/GI	hate of rise of fall of input pulse	Logic inputs, A1, A2		1			V/μs
tw(in)	input pulse width		······································	50			ns
Rext	External timing capacitance	•	54 Family	1.4		30	
''ext	External timing capacitance		74 Family	1.4		40	kΩ
C _{ext}	External timing capacitance		, <u> </u>	0		1000	μF
	Duty cycle	$R_T = 2 k\Omega$				67	
	Daty cycle	RT = MAX Rext				90	%
T _A Operating free-air temperature			54 Family	- 55		125	
		Operating free-air temperature 74 Family		0		70	aС

SN54121, SN74121 MONOSTABLE MULTIVIBRATORS WITH SCHMITT-TRIGGER INPUTS

electrical characteristics over recommended operating free-air temperature range (unless otherwise

	PARAMETER	TEST CO	NDITONS†	MIN	TYP‡	MAX	UNIT
VIH	High-level input voltage at B input	VCC = MIN		2			V
VIL	Low-level input voltage at A input	VCC - MIN				0.8	ν
V _{T+}	Positive-going threshold voltage at B input	VCC = MIN		1	1.55	2	V
VT_	Negative-going threshold voltage at B input	V _{CC} = MIN		0.8	1.35		٧
Vik	Input clamp voltage	V _{CC} = MIN,	I _f = -12 mA			- 1.5	٧
ЮН	High-level output voltage	V _{CC} = MIN,	IOH = MAX	2.4	3.4		٧
Vol	Low-level output voltage	VCC = MIN.	IOL = MAX		0.2	0.4	V
ΙĮ	Input current at maximum input voltage	V _{CC} = MAX,	V _I = 5.5 V			1	mÅ
t	High level innue current	V _{CC} = MAX,	A1 or A2			40	
ΉН	High-level input current	V ₁ - 2.4 V	В			80	μА
	La colonal in the acceptance	VCC = MAX,	A1 or A2			- 1.6	^
IIL	Low-level input current	V _I = 0.4 V	В			- 3.2	mA
	ξ	V- 444V	54 Family	- 20		- 55	
os	Short-circuit output current [§]	V _{CC} = MAX	74 Family	- 18		- 55	mA
1	C In accordant	L/ BAAV			13	25	A
ICC	Supply current	V _{CC} = MAX	Triggered		23	40	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25 \,^{\circ}\text{C}$

	PARAMETER	TEST CON	DITIONS	MIN	TYP	MAX	UNIT
^t PLH	Propagation delay time, low-to-high- level Q output from either A input				45	70	ns
tPLH	Propagation delay time, low-to-high- level Ω output from B input		C _{ext} = 80 pF,		35	55	ns
tPHL	Propagation delay time, high-to-low level Q output from either A input	C _I = 15 pF,	R _{int} to VCC		50	80	ns
[†] PHL	Propagation delay time, high-to-low level $\vec{\Omega}$ output from 8 input	$R_L = 400 \Omega$, See Note 4			40	65	ns
tw(out)	Pulse width obtained using internal timing resistor		C _{ext} = 80 ρF, R _{int} to V _{CC}	70	110	150	ns
tw(out)	Pulse width obtained with zero timing capacitance		C _{ext} = 0, R _{int} to V _{CC}		30	50	กร
	Pulse width obtained using]	$C_{\text{ext}} = 100 \text{ pF},$ $R_{\text{T}} = 10 \text{ k}\Omega$	600	700	800	ns
^t w(out)	external timing resistor		$C_{\text{ext}} = 1 \mu\text{F},$ $R_{\text{T}} = 10 \text{k}\Omega$	6	7	8	ms

NOTE 4: Load circuits and voltage waveforms are shown in Section 1.

 $^{^{\}ddagger}$ All typical values are at V_{CC} = 5 V, T_A = 25 °C. † Not more than one output should be shorted at a time.

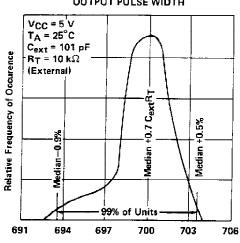
TYPICAL CHARACTERISTICS[†]

10%

~50

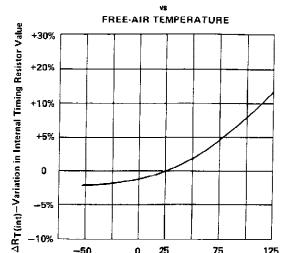
DISTRIBUTION OF UNITS

OUTPUT PULSE WIDTH



tw(out)-Output Pulse Width-ns

VARIATION IN INTERNAL TIMING RESISTOR VALUE



25 TA-Free-Air Temperature-°C

75

125

FIGURE 1

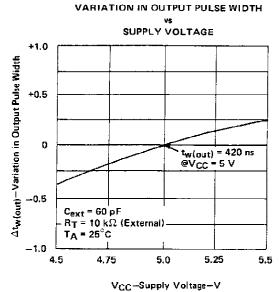
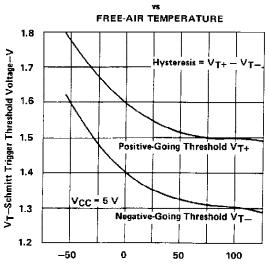


FIGURE 2

SCHMITT TRIGGER THRESHOLD VOLTAGE



TA-Free-Air Temperature-°C

FIGURE 3

FIGURE 4

[†]Data for temperatures below 0°C and above 70°C are applicable for SN54121.



TYPICAL CHARACTERISTICS[†] (continued)

100 ns

10 ns

Vcc = 6

10--5

VARIATION IN OUTPUT PULSE WIDTH FREE-AIR TEMPERATURE 1.0% Atw(out)-Variation in Output Pulse Width Vcc = 5 V CT = 60 pF +0.5% $R_T = 10 \text{ k}\Omega$ 0% t_{w(out)} = 420 ns @ T_A = 25°C 0.5% -1.0% 100 -50

TIMING RESISTOR VALUE 10 ms 1 ms tw(out)-Output Pulse Width 100 µs 10 μs 1 μs

OUTPUT PULSE WIDTH

TA-Free-Air Temperature-°C

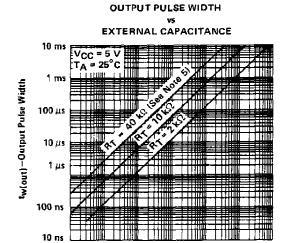
RT—Timing Resistor Value- $k\Omega$

10

100

FIGURE 5

FIGURE 6



Cext —Timing Capacitance—F

10-7

FIGURE 7

NOTE 5: These values of resistance exceed the maximum recommended use over the full temperature range of the SN54121. †Data for temperatures below 0 °C and above 70 °C are applicable for SN54121.

10-9

10-11

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PACKAGE OPTION ADDENDUM



ti.com 23-Apr-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9755301QCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
5962-9755301QDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
5962-9755301QDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SN54121J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54121J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN74121D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74121D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74121DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74121DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74121N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74121N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74121N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74121N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74121NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74121NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SNJ54121J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54121J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54121W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54121W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54121WA	ACTIVE	CFP	WA	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54121WA	ACTIVE	CFP	WA	14	1	TBD	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



PACKAGE OPTION ADDENDUM

23-Apr-2005

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14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



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- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.









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5962-9755301QCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
5962-9755301QDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN54121J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN74121D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74121DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74121DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74121DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74121DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74121DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74121N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74121N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74121NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74121NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74121NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74121NSRG4	ACTIVE	so	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54121J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54121W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54121WA	ACTIVE	CFP	WA	14	1	TBD	A42	N / A for Pkg Type

(1) The marketing status values are defined as follows:

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TBD: The Pb-Free/Green conversion plan has not been defined.

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Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



PACKAGE OPTION ADDENDUM

9-Oct-2007

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

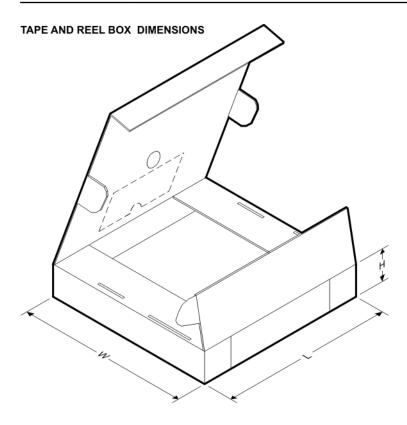
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74121DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74121NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74121DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74121NSR	SO	NS	14	2000	346.0	346.0	33.0

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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